



PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/917,127

Filed: July 27, 2001

For: METHOD FOR FABRICATING A
CHIP SCALE PACKAGE USING WAFER
LEVEL PROCESSING AND DEVICES
RESULTING THEREFROM

Confirmation No.: 3326

Examiner: M. Trinh

Group Art Unit: 2822

Attorney Docket No.: 2269-3572.1US
(97-1243.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

12/2/2003
Date

Signature

Leah J. Barrow
Name (Type/Print)

RECEIVED
DEC - 9 2003
TECHNOLOGY CENTER 2800

AMENDMENT UNDER 37 C.F.R. §1.116

Mail Stop AF
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed October 16, 2003, the three-month shortened statutory period for response to which expires on January 16, 2004. This response is submitted on or before two months from the mailing date of the Final Office Action.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Amendments to the Drawings begin on page 9 of this paper and include both attached replacement sheets and annotated sheets showing changes.

Remarks begin on page 10 of this paper.